

Exhibit E

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Ed:

We brought an idea to you in February which had, what we thought at the time, gave two results: The improvement of wetting and the improvement of paste release. MPM provided us with the opportunity to evaluate our theories in two of their labs. The outcome of those evaluations showed no significant change in wetting, but more consistent release as well better defined depositions of solder paste during printing.

Continuing my relations with MPM, I would like to at least provide MPM with the first opportunity to license this technology. The technology can be applied to applications such as thick stencils for creating solder balls for BGA, μ BGA, CSP, as well as small apertures for improved release for fine pitch components, DCA, and also printing of adhesive.

Eric & I have made several unsuccessful attempts to contact you via phone. We are just curious to what MPM's intentions are prior to pursuing other licensing agreements. In addition, I am following up on the status on the reimbursements of the hotel (\$183.05) and airfare (\$571.27) from my visit.

Looking forward to hearing from you,

Allen

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